

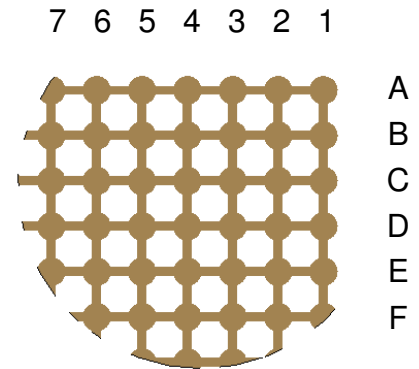
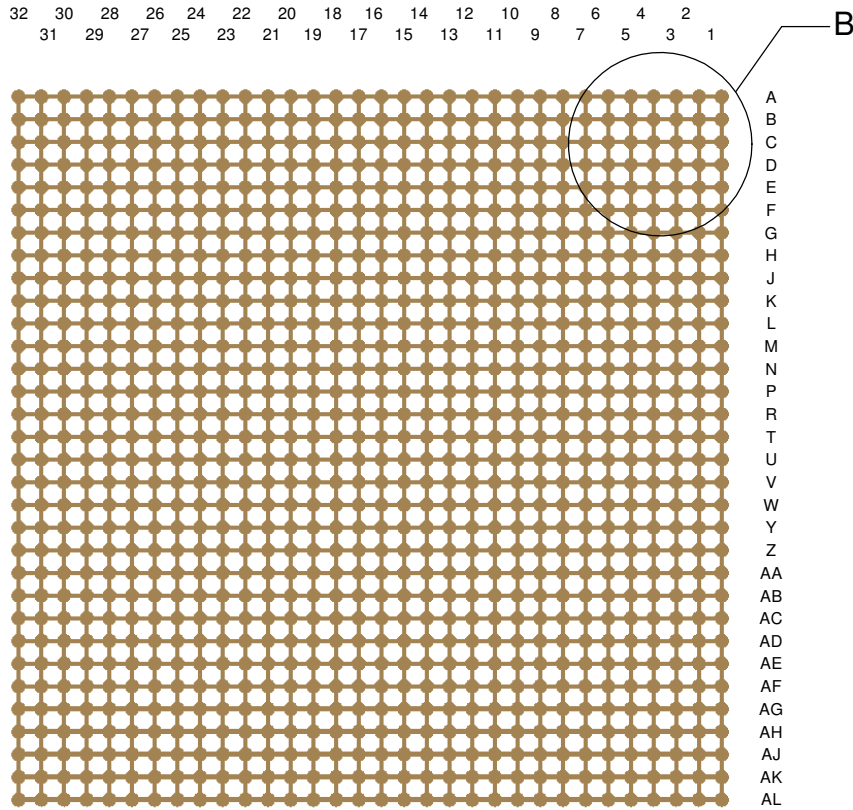
- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.635mm [25 MIL].
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm [20 MIL].
  - 5) PAD Cu DIAMETER: 0.685mm [27 MIL].
  - 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
  - 7) DUMMY DIE IS OPTIONAL.
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

SECTION A-A

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA1024T1.0C-BUS	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA1024T1.0C-BUS-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA1024T1.0-BUS	Sn63/Pb37	NO	NO	NO
LBGA1024T1.0-BUS-D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.XX	+/- 0.01	DRAWN J. Hines		8/3/2014						
X.XXX	+/- 0.005	ENG M. Hart		8/3/2014		<b>TITLE</b> <b>LBGA1024T1.0-BUS</b> <b>ALL PADS SHORTED</b>				
X.XXXX	+/- 0.0005	MFG								
ANGLES +/- 0.5°		THIRD ANGLE PROJECTION		SCALE 3:1		SIZE A		DRAWING NO. 513201		REV A
ALL DIMENSIONS IN INCHES <input type="checkbox"/> MILLIMETERS <input checked="" type="checkbox"/>		QA		CUST		DO NOT SCALE DRAWING		SHEET 1 OF 3		
		REVISED								

# BALL VIEW



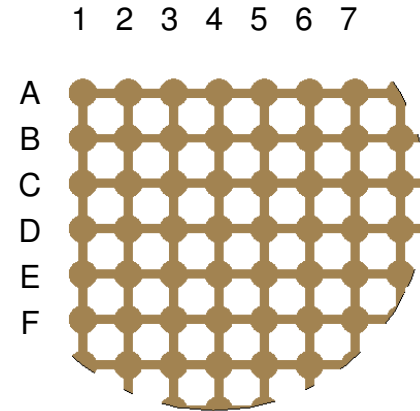
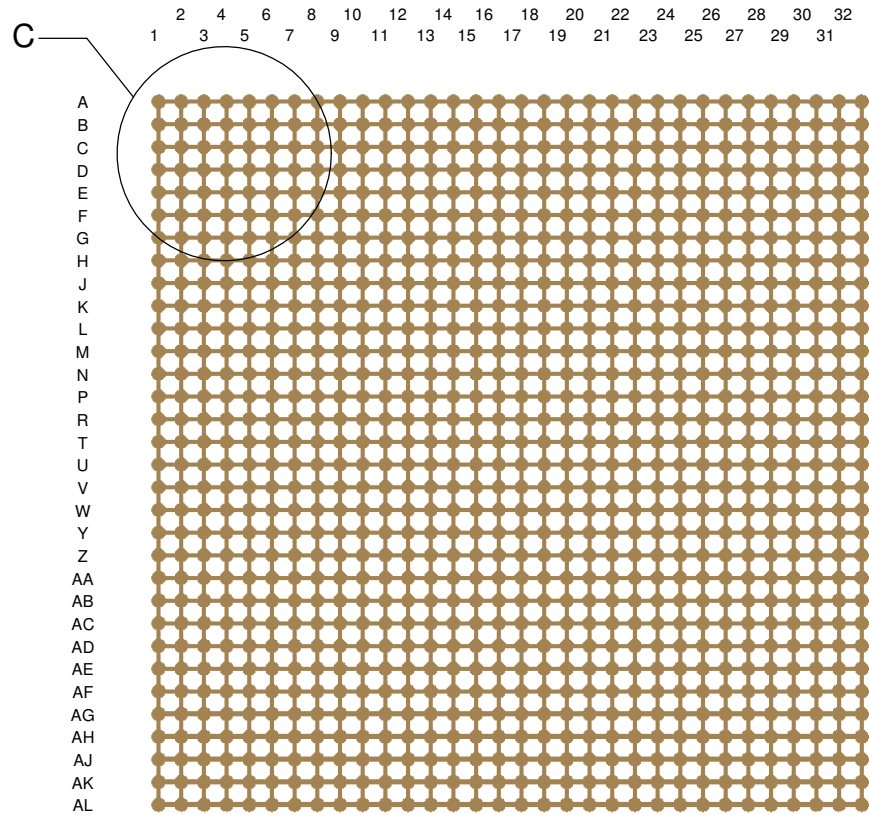
DETAIL B  
SCALE 6 : 1  
ALL PADS  
CONNECTED

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm [27 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.204mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.508mm [20 MIL].

<b>TopLine</b> ®			
TITLE <b>LBGA1024T1.0-BUS ALL PADS SHORTED</b>			
SCALE 3:1	SIZE A	DRAWING NO. 513201	REV A
DO NOT SCALE DRAWING		SHEET 2   OF 3	

BOTTOM SIDE (TOP X-RAY VIEW)



DETAIL C  
 SCALE 6 : 1  
 ALL PADS  
 CONNECTED

<b>TopLine</b> ®			
TITLE LBGA1024T1.0-BUS ALL PADS SHORTED			
SCALE 3:1	SIZE A	DRAWING NO. 513201	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 3	